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December 2013

## FPAB20BH60B PFC SPM<sup>®</sup> 3 Series for Single-Phase Boost PFC

## **Features**

- UL Certified No. E209204 (UL1557)
- 600 V 20 A Single-Phase Boost PFC with Integral Gate Driver and Protection
- Very Low Thermal Resistance Using A<sub>2</sub>O<sub>3</sub> DBC Substrate
- Full-Wave Bridge Rectifer and High-Performance Output Diode
- Built-in NTC Thermistorfor Temperature Monitoring
- · Optimized for 20kHz Switching Frequency
- Isolation Rating: 2500 Vrms/min.

## **Applications**

• Single-Phase Boost PFC Converter

## **Related Source**

- AN-9090 PFC SPM 3 Series User's Guide
- AN-9091 Boost PFC Inductor Design Guide

## **General Description**

The FPAB20BH60B is an advanced PFC SPM® 3 module providing a fully-featured, high-performance Boost PFC (Power Factor Correction) input power stage for consumer, medical, and industrial applications. These modules integrate optimized gate drive of the built-in IGBT to minimize EMI and losses, while also providing multiple on-module protection features including under-voltage lockout, over-current shutdown, thermal monitoring, and fault reporting. These modules also feature a full-wave rectifier, and high-performance output diode for additional space savings and mounting convenience.

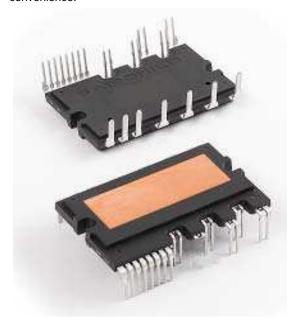


Figure 1. Package Overview

## **Package Marking & Ordering Information**

Device	Device Marking	Package	Packing Type	Quantity	
FPAB20BH60B	FPAB20BH60B	SPMIC-027	Rail	10	

## **Integrated Power Functions**

• PFC converter for single-phase AC / DC power conversion (please refer to Figure 3)

## Integrated Drive, Protection, and System Control Functions

- For IGBTs: gate drive circuit, Over-Current Protection (OCP), control supply circuit Under-Voltage Lock-Out (UVLO) Protection
- Fault signal: corresponding to OC and UV fault
- Built-in thermistor: temperature monitoring
- Input interface: active-HIGH interface, works with 3.3 / 5 V logic, Schmitt-trigger input

## **Pin Configuration**

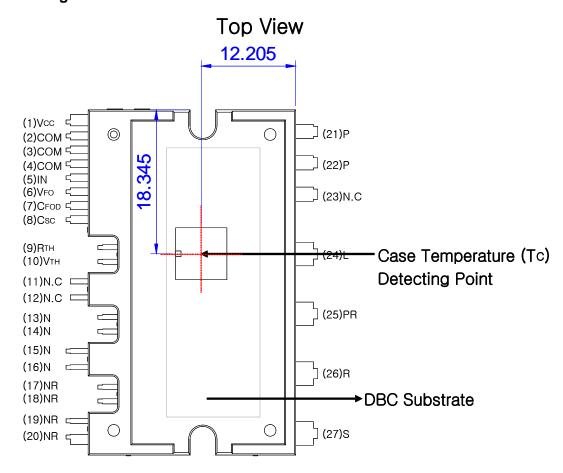


Figure 2. Top View

## Notes :

1. For the measurement point of case temperature( $T_{\text{C}}$ ), please refer to Figure 2.

## **Pin Descriptions**

Pin Number	Pin Name	Pin Description	
1	V <sub>CC</sub>	Common Bias Voltage for IC and IGBT Driving	
2,3,4	COM	Common Supply Ground	
5	IN	Signal Input for IGBT	
6	V <sub>FO</sub>	Fault Output	
7	C <sub>FOD</sub>	Capacitor for Fault Output Duration Selection	
8	8 C <sub>SC</sub> Capacitor (Low-Pass Filter) for Over-Current Detection		
9	R <sub>(TH)</sub>	Series Resistor for The Use of Thermistor	
10	V <sub>(TH)</sub>	Thermistor Bias Voltage	
11,12	N.C	No Connection*	
13~16	N	IGBT Emitter	
17~20	N <sub>R</sub>	Negative DC-Link of Rectifier	
21,22	Р	Positive Rail of DC-Link	
23 N.C No Connection		No Connection	
24	L	L Reactor Connection Pin	
25	$P_{R}$	Positive DC-Link of Rectifier	
26	R	AC Input for R-Phase	
27	S	AC Input for S-Phase	

<sup>\* 11</sup>th and 12th pins are cut. Please refer to package outline drawings for more detail.

## **Internal Equivalent Circuit and Input/Output Pins**

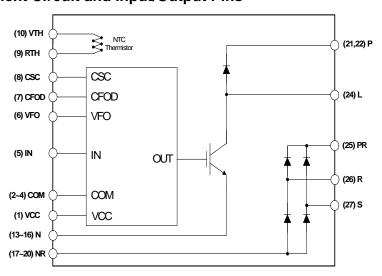


Figure 3. Internal Block Diagram

## **Absolute Maximum Ratings** ( $T_J = 25^{\circ}C$ , unless otherwise specified.)

## **Converter Part**

Symbol	Item Condition		Rating	Unit
V <sub>i</sub>	Supply Voltage	Applied between R - S	264	$V_{rms}$
V <sub>i(Surge)</sub>	Supply Voltage (Surge)	Applied between R - S	500	V
V <sub>PN</sub>	Output Voltage	Applied between P - N	450	<b>V</b>
V <sub>PN(Surge)</sub>	Output Voltage (Surge)	Applied between P - N	500	٧
V <sub>CES</sub>	Collector - Emitter Voltage		600	V
I <sub>C</sub>	Each IGBT Collector Current	T <sub>C</sub> = 25°C, T <sub>J</sub> < 150°C	20	Α
I <sub>CP</sub>	Each IGBT Collector Current (Peak)	$T_C = 25$ °C, $T_J < 150$ °C, Under 1ms Pulse Width	40	Α
P <sub>C</sub>	Collector Dissipation	T <sub>C</sub> = 25°C	89	W
$V_{RRM}$	Repititive Peak Reverse Voltage		600	V
I <sub>FSM</sub>	Peak Forward Surge Current	Single Half Sine-Wave	250	Α
TJ	Operating Junction Temperature		-40 ~ 150	°C

## **Control Part**

Symbol	Item	Condition	Rating	Unit
V <sub>CC</sub>	Control Supply Voltage	Applied between V <sub>CC</sub> - COM	20	٧
V <sub>IN</sub>	Input Signal Voltage	Applied between IN - COM	-0.3 ~ V <sub>CC</sub> +0.3	V
V <sub>FO</sub>	Fault Output Supply Voltage	Applied between V <sub>FO</sub> - COM	-0.3 ~ V <sub>CC</sub> +0.3	٧
I <sub>FO</sub>	Fault Output Current	Sink Current at V <sub>FO</sub> Pin	5	mA
V <sub>SC</sub>	Current Sensing Input Voltage	Applied between C <sub>SC</sub> - COM	-0.3 ~ V <sub>CC</sub> +0.3	V

## **Total System**

Symbol	Item Condition		Rating	Unit
T <sub>STG</sub>	Storage Temperature		-40 ~ 125	°C
V <sub>ISO</sub>	Isolation Voltage	60 Hz, Sinusoidal, AC 1 Minute, Connect Pins to Heat Sink Plate	2500	V <sub>rms</sub>

## **Thermal Resistance**

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
$R_{\theta(j-c)Q}$	Junction to Case Thermal Resistance	IGBT	-	-	1.4	°C/W
$R_{\theta(j-c)F}$		FRD	-	-	1.4	°C/W
$R_{\theta(j-c)R}$		Rectifier (per 1 / 4 module)	-	-	2.1	°C/W

## **Electrical Characteristics** ( $T_J = 25$ °C, unless otherwise specified.)

## **Converter Part**

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
V <sub>CE(SAT)</sub>	IGBT Saturation Voltage	V <sub>CC</sub> = 15 V, V <sub>IN</sub> = 5 V, I <sub>C</sub> = 20 A	1	2.3	3.0	V
$V_{FF}$	FRD Forward Voltage	I <sub>F</sub> = 20 A	1	1.8	2.5	V
$V_{FR}$	Rectifier Forward Voltage	I <sub>F</sub> = 20 A	1	1.2	1.5	V
t <sub>ON</sub>	Switching Times	$V_{PN} = 400 \text{ V}, V_{CC} = 15 \text{ V}, I_{C} = 20 \text{ A}$	-	450	-	ns
t <sub>C(ON)</sub>		$V_{IN} = 0 \text{ V} \leftrightarrow 5 \text{ V}$ , Inductive Load	-	200	-	ns
t <sub>OFF</sub>		(Note 2)	1	350	-	ns
t <sub>C(OFF)</sub>			1	80	-	ns
t <sub>rr</sub>			1	70	-	ns
I <sub>rr</sub>			1	6	-	Α
I <sub>CES</sub>	Collector - Emitter Leakage Current	$V_{CE} = V_{CES}$	-	-	250	μА

2. to<sub>N</sub> and t<sub>OFF</sub> include the propagation delay of the internal drive IC. t<sub>C(ON)</sub> and t<sub>C(OFF)</sub> are the switching time of IGBT itself under the given gate driving condition internally. For the detailed information, please see Figure 4.

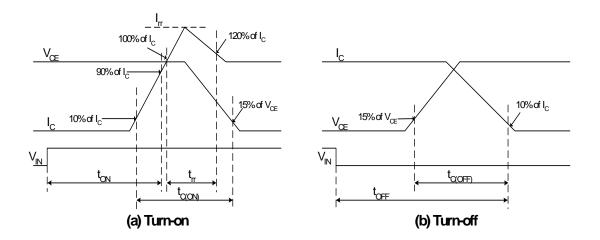


Figure 4. Switching Time Definition

## **Control Part**

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
I <sub>QCCL</sub>	Quiescent V <sub>CC</sub> Supply Current	V <sub>CC</sub> = 15 V, IN = 0 V V <sub>CC</sub> - COM	-	-	26	mA
V <sub>FOH</sub>	Fault Output Voltage	$V_{SC} = 0 \text{ V}, V_{FO} \text{ Circuit: } 4.7 \text{ k}\Omega \text{ to 5 V Pull-up}$	4.5	-	-	V
V <sub>FOL</sub>		$V_{SC}$ = 1 V, $V_{FO}$ Circuit: 4.7 k $\Omega$ to 5 V Pull-up	-	-	0.8	V
V <sub>SC(ref)</sub>	Over-Current Trip Level	V <sub>CC</sub> = 15 V		0.5	0.55	٧
UV <sub>CCD</sub>	Supply Circuit Under-Voltage	Detection Level		11.9	13.0	V
UV <sub>CCR</sub>	Protection	Reset Level		12.4	13.2	V
t <sub>FOD</sub>	Fault-Out Pulse Width	C <sub>FOD</sub> = 33 nF (Note 3)		1.8	2.0	ms
V <sub>IN(ON)</sub>	ON Threshold Voltage	Applied between IN - COM		-	-	٧
V <sub>IN(OFF)</sub>	OFF Threshold Voltage			-	0.8	V
R <sub>TH</sub>	Resistance of Thermistor	@ T <sub>TH</sub> = 25°C (Note 4, Figure 5)	-	47.0	-	kΩ
		@ T <sub>TH</sub> = 100°C (Note 4, Figure 5)	-	2.9	-	kΩ

- Notes:
  3. The fault-out pulse width  $t_{FOD}$  depends on the capacitance value of  $C_{FOD}$  according to the following approximate equation:  $C_{FOD} = 18.3 \times 10^{-6} \times t_{FOD}$  [F].

  4.  $T_{TH}$  is the temperature of know case temperature  $(T_C)$ , please make the experiment considering your application.

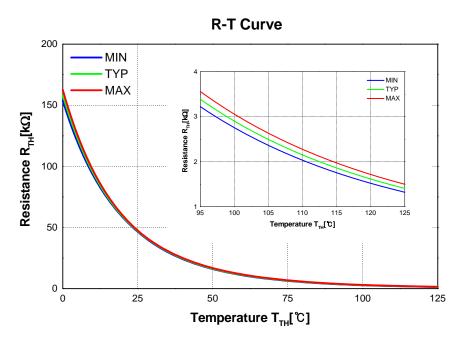


Figure 5. R-T Curve of the Built-In Thermistor

## **Recommended Operating Condition**

Symbol	Item	Condition	Min.	Тур.	Max.	Unit
V <sub>i</sub>	Input Supply Voltage	Applied between R - S	187	220	253	$V_{rms}$
V <sub>PN</sub>	Output Voltage	Applied between P - N	-	380	400	V
V <sub>CC</sub>	Control Supply Voltage	Applied between V <sub>CC(L)</sub> - COM	13.5	15.0	16.5	V
dV <sub>CC</sub> /dt	Control Supply Variation		-1	-	1	V/μs
f <sub>PWM</sub>	PWM Input Frequency	T <sub>J</sub> ≤ 150°C	-	20	-	kHz
l <sub>i</sub>	Allowable Input Current	$T_C$ < 90°C, $V_i$ = 220 V, $V_{PN}$ = 380 V $V_{PWM}$ = 20 kHz	-	-	20	A <sub>peak</sub>

## **Mechanical Characteristics and Ratings**

Item	Co	ondition	Min.	Тур.	Max.	Unit
Mounting Torque	Mounting Screw: M3	Recommended 0.62 N• m	0.51	0.62	0.72	N• m
Device Flatness	See Figure 6		0	-	+120	μm
Weight			-	15.00	-	g

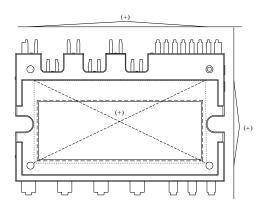
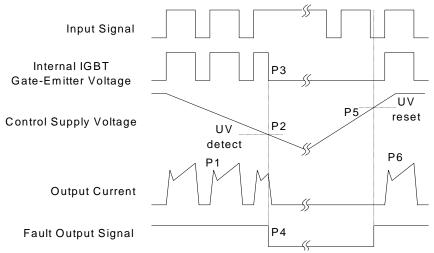


Figure 6. Flatness Measurement Position



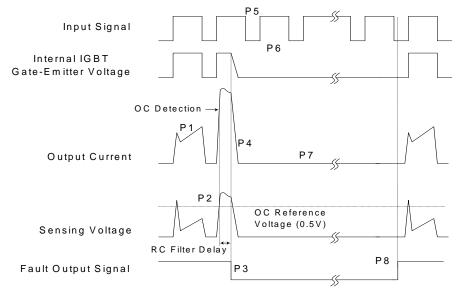


P1: Normal operation: IGBT ON and conducting current

P2 : Under-voltage detection P3 : IGBT gate interrupt P4 : Fault signal generation P5 : Under-voltage reset

P6: Normal operation: IGBT ON and conducting current

Figure 7. Under-Voltage Protection



P1 : Normal operation: IGBT ON and conducting current

P2: Over current detection

P3 : IGBT gate interrupt / fault signal generation

P4 : IGBT is slowly turned off

P5: IGBT OFF signal

P6: IGBT ON signa: but IGBT cannot be turned on during the fault output activation

P7: IGBT OFF state

P8 : Fault output reset and normal operation start

Figure 8. Over-Current Protection

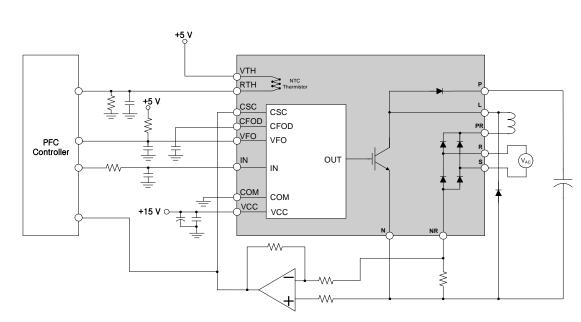


Fig. 9. Application Example

#### Notes

- 5. Each capacitors should be located as close to PFC  $\mathrm{SPM}^{\$}$  product pins as possible.
- 6. It's recommended that anti-parallel diode should be connected with IGBT.

## **Detailed Package Outline Drawings** LEAD PITCH (TOLERANCE: ±0.30) A: 1.778 (2.31) (1.55) B: 2.050 C: 2.531 44.20 43.80 3.20 (13.20)6.8 ψψ (R0.70)13,335 4.30 (2.76) 2X 8.754 4.445 20,447 фф 6.90 DETAIL A (0.70) 2X 31,56 7.92 4X 7.32 4.30 2X 3.70 2X 1.40 7X 1.20 7X 15.78 NOTES: UNLESS OTHERWISE SPECIFIED A) THIS PACKAGE DOES NOT COMPLY 4.00 DETAIL B TO ANY CURRENT PACKAGING STANDARD 11.62 11.24 B) ALL DIMENSIONS ARE IN MILLIMETERS C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS

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